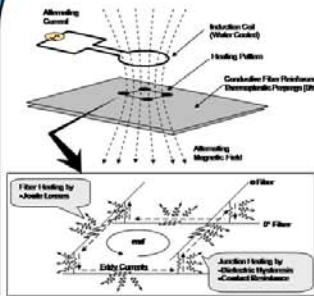


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PROCESS OVERVIEW

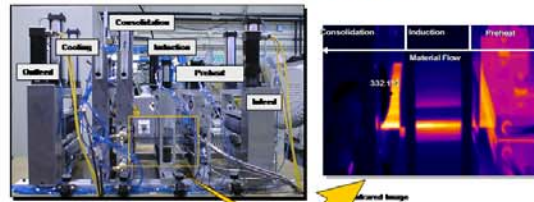


- Conductive Loops Formation at Prepreg Interfaces
- Non-zero Orientation Angles Required
- Heating Locations and the Mechanisms
 - Carbon fibers: Joule Heating
 - Fiber Junctions: Dielectric or Contact Resistance
- Layered Stack of Unconsolidated Prepregs
 - Contact Resistance Heating Dominance
- Parameters: Fiber resistance, Contact Resistance

-Process Advantage

- Heating/Consolidation of Multiple Prepregs
- Volumetric Heating in Thickness Direction
- Internal Heat Generation
- No External Heat Sources and
- No Magnetic Field Susceptors
Ex.) metal mesh, ferromagnetic particles

APPLICATION: RAIL (RAPID AUTOMATED INDUCTION LAMINATION) PROCESS DEVELOPED BY UD-CCM

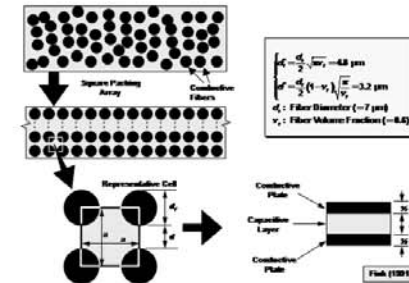


- 8-Ply Laminator (AS4/PEI Prepreg)
- Processing Speed: 1.5-3.7 m/min
- Heating Rate: 10-100 °C/sec
- Issue: High Likelihood of Non-uniform Heat Generation Profiles in Thickness Direction due to Heating only at the Prepreg Interfaces
- Objective: Achieve Uniform Through-Thickness Temperature Field

MODELING: PREPREG MICROSTRUCTURE

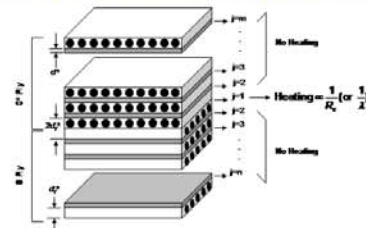
Assumptions

- Square Packing Array Assumption
- For Cross-Section of Prepreg
- Conductive Plates and Capacitive Layers
 - Conductive Plates: Heat Source for Contact Resistance Heating
 - Capacitive Layers: Electric Insulators between Conductive Plates for Contact Resistance Heating
- 16 Conductive Plates and 16 Capacitive Layers for a AS4/PEI Prepreg



$$\left\{ \begin{aligned} \phi &= \frac{d_f}{2} \sqrt{\pi} = 4.8 \mu\text{m} \\ \phi^* &= \frac{d_f}{2} \sqrt{\pi} \left(\frac{1}{\nu_f} \right) = 3.2 \mu\text{m} \\ d_f &: \text{Fiber Diameter } (\approx 7 \mu\text{m}) \\ \nu_f &: \text{Fiber Volume Fraction } (\approx 0.8) \end{aligned} \right.$$

MODELING: PREPREG MICROSTRUCTURE



Assumptions

- Layered stack of unconsolidated prepregs
- Heating: only at prepreg interfaces having non-zero orientation angles
- Contact resistance heating dominance
- L: contact resistance between single fibers at the interface

MODELING: HEAT GENERATION/TRANSFER

$$\rho C_p \frac{\partial T}{\partial t} = k_z \frac{\partial^2 T}{\partial z^2} + g(z)$$

- 1-Dimensional Heat Transfer
- Through-Thickness Heating
- Transient (Unsteady State)
- Heat Source Term

• Boundary Conditions

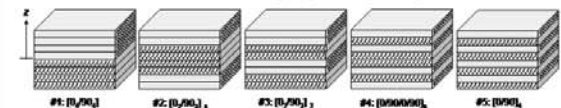
- Adiabatic ($h = 0$)
- Natural Convection ($h = 10 \text{ W/(m}^2\text{K)}$)
- Fixed Surface Temperature ($T_s = T_\infty$)

Material and Process Parameters

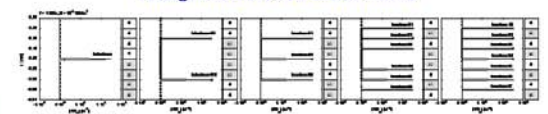
Electrical resistivity of carbon fiber	$\rho_f = 1530 \mu\Omega \text{ cm}$
Dielectric constant of PEI	$\epsilon = 3.5$ (room temperature)
Loss factor of PEI	$\tan \delta = 0.0016$
Induction frequency	$f = 1 \text{ MHz}$
Contact resistance	$\lambda = 1.25 \times 10^6 - 1.25 \times 10^7 \Omega$
Volumetric heat capacity of AS4/PEI	$\rho C_p = 2 \times 10^6 \text{ J/(m}^3 \text{ } ^\circ\text{C)}$
Thermal conductivity of AS4/PEI (z-dir)	$k_z = 0.28$

MODELING: HEAT GENERATION/TRANSFER

Selected Stacking Sequences (8 Piles)



Through-Thickness Heat Source Profiles



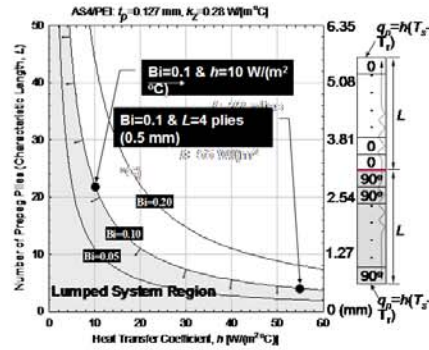
RESULTS – BIOT NUMBER

Stacking: Heating only at the Center of the Stack (N number of 0° Piles and N number of 90° Piles, Symmetric)

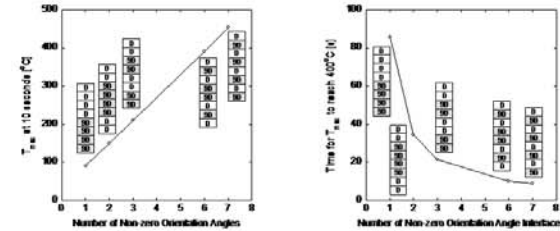
Parameters: Boundary Condition and Number of Prepreg Piles

Contour Plot of Biot Number

- Determination of Maximum Heat Transfer Coefficient for Lumped System Approach (Uniform Through-thickness Heating)
- Determination of Maximum Number of Prepreg Piles for Uniform Through-thickness Heating
- More Complicated Stacking Sequences
 - Shorter Characteristic Length for Heat Diffusion
 - Lower Biot Number for More Uniform Heating



RESULTS: STACKING SEQUENCE EFFECTS



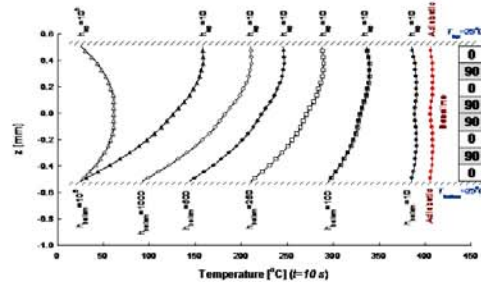
Benefit of Stacking Sequence Change

- Augmented heating and more uniform temperature field
- Maximum Temperature (10 seconds, Adiabatic)
- Simple linear increment due to additional heating locations
- Augmented heating intensity in thickness direction
- Possible control of internal heat generation profile to obtain more uniform temperature field in thickness direction
- Time for Temperature (400°C, Adiabatic)
- Reduced time to reach melting/consolidation temperature of PEI

RESULTS: BOUNDARY CONDITIONS EFFECTS

Through-Thickness Temperature Field (10 seconds) with Asymmetric Boundary Conditions in Equipment

- Non-uniformity in through-thickness temperature field nevertheless in spite of low Biot Number
- Importance of processing equipment design considering boundary conditions



FUTURE WORK

Strategies for Uniform Temperature Field

Given stacking sequence for desired mechanical properties

- Possible non-uniformity of temperature
- Boundary condition adjustment for temperature uniformity (ex. Heated tool surface, forced convection)
- Control of induction power and other processing parameters to maintain or increase processing speed and heating rate

Fixed boundary conditions in processing equipment

- Possible non-uniformity of temperature
- Stacking sequence change adjustment for uniform temperature
- Control of induction power and other processing parameters to maintain or increase processing speed and heating rate

Experimental Validation of Heating Mechanism and Model

- Heating rate and temperature measurement in short time scale to neglect lateral heat diffusion
- Consideration angle-ply [0/90, 0< 90°] change of contact resistance value with angle and contact area between fibers at the interface

3-Dimensional Heat Transfer Analysis

- To consider lateral (in-plane) heat diffusion
- To establish generalized design tool for induction lamination
- Coil design for uniform in-plane heating patterns

ACKNOWLEDGEMENTS

- This work is supported by the Army Research Laboratory through the Composite Materials Technology program.